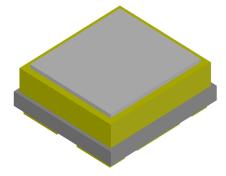
JSFON



# **OC-VC** series

# **Product Specification**

Product	3532 VCSEL Emitter
Part Number	OCVC32-7258V8510-V0
Issue Date	2019/10/14



#### Features

- Vertical Cavity Surface Emitting Laser technology
- Package size = 3.5mm x 3.2mm x 1.3mm
- Pulse Output power 1W emitter
- Peak wavelength  $\lambda_p$  =850nm
- Divergence angles= 72°x 58°
- Wavelength stabilized (0.07nm per °C)
- Narrow spectral width (<1nm)
- RoHS
- Photo Diode inside

### Applications

- 3D depth sensing
- Gesture sensing
- Flood illuminator



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# **Product Nomenclature**

The product name is designated as below:

# <u>OCVCAB</u> – <u>CDEFGHIJK</u>

#### Designation:

OCVC = Orient-Chip Technology Co.,LTD VCSEL Series Product. AB = Package size  $_{(1)}$ CDEF = Divergence Angle  $_{(2)}$ G = Internal Code HI = Wavelength  $_{(3)}$ JK = Pulse mode Output Power  $_{(4)}$ 

#### Notes

1. Package	e Size:
Symbol	Description
32	3.5mm x 3.2mm

#### 2. Divergence Angle:

U	5
Symbol	Description
5040	50° x 40°
6045	60° x 45°
7258	72° x 58°
9070	90° x 70°
1190	110° x 90°

#### 3. Wavelength:

Symbol	Description
85	850nm
94	940nm

#### 4. Pulse mode Output Power:

Symbol	Description
05	0.5W
10	1W
20	2W
30	3W
40	4W



# Maximum Ratings (Ta = 25 °C)

Parameter	Symbol	Values	Unit
Operating temperature range	T <sub>op</sub>	-20 ~ 85	°C
Storage temperature range	T <sub>stg</sub>	-40 ~ 85	°C
Maximum package SMT solder Reflow temperature		260°C 10seconds	°C

### Characteristics(Ta = 25 °C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Pulse Output power	Po	I <sub>F</sub> = 1.35 A	900	1150	-	mW
Wavelength	$\lambda_{p}$	I <sub>F</sub> = 1.35 A	840	850	860	nm
Forward Voltage	Vf	I <sub>F</sub> = 1.35 A	1.7	2.0	2.3	V
Threshold current	l <sub>th</sub>		-	180	-	mA
Power Conversion Efficiency	PCE	I <sub>F</sub> = 1.35 A	-	41	-	%
Wave Shift	∆λ/∆Τ	I <sub>F</sub> = 1.35 A	-	0.07	-	nm/°C
Slope Efficiency			-	0.98	-	W/A

Note:

- Forward Voltage tolerance is ±0.1 V, Radiant Intensity tolerance is ±10% Others measurement allowance is ±10%.
- 2. VCSEL is mounted on PCB and measured with operating bias current @ 1.35A,10ms
- 3. Due to the special conditions of the manufacturing processes of VCSEL, the typical data of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

# Photodiode Electrical / Optical Characteristics(Ta = 25 °C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	Vf	I <sub>F</sub> = 10 mA	0.5		1.3	V
Reverse Breakdown Voltage	$V_{BR}$	I <sub>R</sub> = 100 uA	35			V
Reverse Dark Current	I <sub>D</sub>	V <sub>R</sub> = 10 V		2	10	nA
Light Current	ΙL	$V_R = 5 V$		0.5		uA
Peak Sensing Wavelength	$\lambda_{p}$			850		nm



# Radiometric Power Bin Structure at 1350mA

or	Bin Code	Minimum Radiometric Power (mW)	Typical Radiometric Power (mW)
ed 850	B1	900	1150
The flux	bin of the product	e of ±10% on flux and power measurer t may be modified for improvement with <b>gth Bin Structure at</b>	out notice.
		~	
Color	Bin Code	Centroid Wavelength	
Color	Bin Code 85	Centroid Wavelength 850	

# Forward Voltage Bin Structure at 1350mA

Color	Bin Code	Typical Voltage (V)	Maximum Voltage (V)
Infrared 850	A1	2.0	2.3

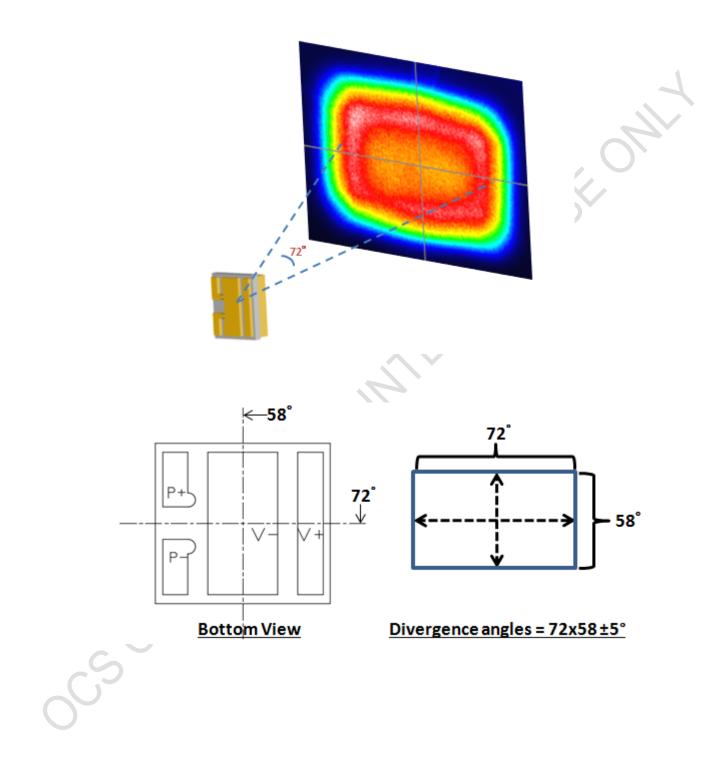
• OCS maintain a tolerance of ±0.1V for Voltage measurements.

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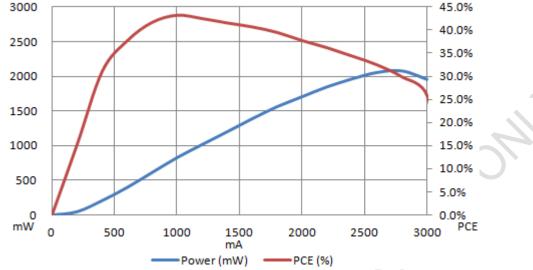


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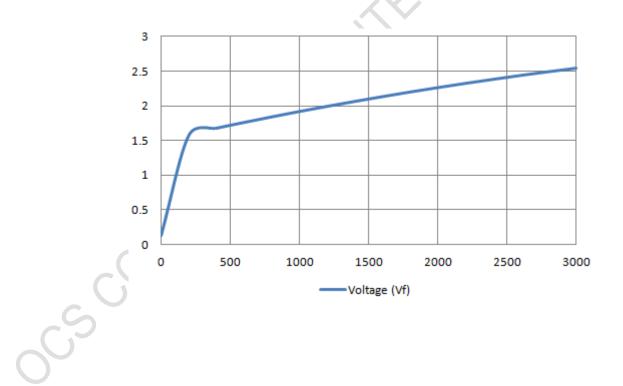
Divergence angles corresponds to the direction



# RIENT-CHIP Pulse Output Power vs. Forward Current

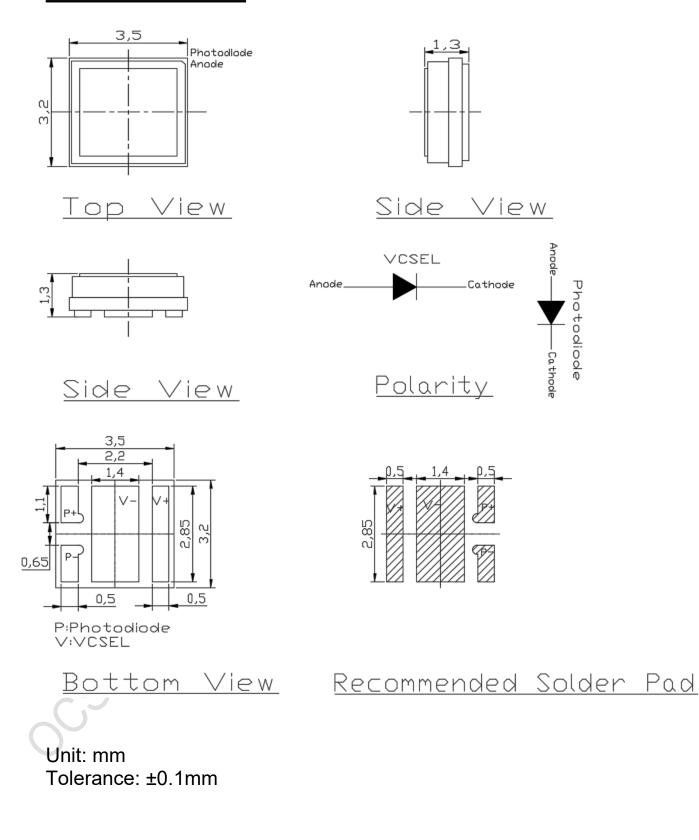


# Forward Voltage vs. Forward Current





■ <u>Outline Dimension</u>





- Cleaning
- 1. If washing is required, recommend to use alcohol as a solvent.
- 2. Recommend to avoid cleaning the VCSEL by ultrasonic. If necessary, pre-test the VCSEL is necessary to confirm whether any damage occur after the process.

# Precautions for use

#### 1. Over-current-proof

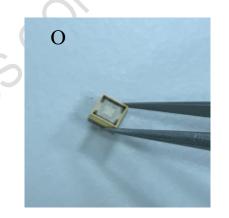
1.1 Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

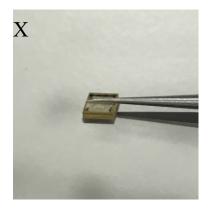
#### 2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The VCSEL should be kept at 30°C or less and 90%RH or less.
- 2.3 After opening the package: The VCSEL floor life is 1 year under 30°C or less and 60% RH or less. If unused VCSEL remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the VCSEL have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: 60±5°C for 24 hours.

#### 3. Handling indications

3.1 During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound. In general, VCSEL should only be handled at the housing. This also applies to VCSEL without a diffuser, since the surface can also become scratched.

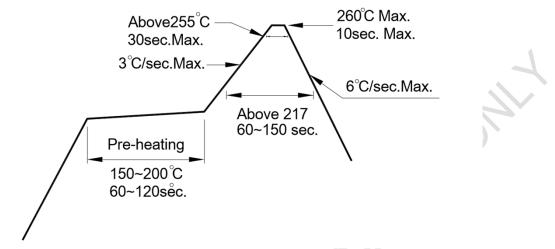






#### 4. Soldering Condition

4.1 Pb-free solder temperature profile (JEDEC-STD-020 latest version compliant)



- 4.2 Reflow soldering should not be done more than two times.
- 4.3 When soldering, do not put stress on the VCSEL during heating.
- 4.4 After soldering, do not warp the circuit board.

#### 5. Soldering Iron

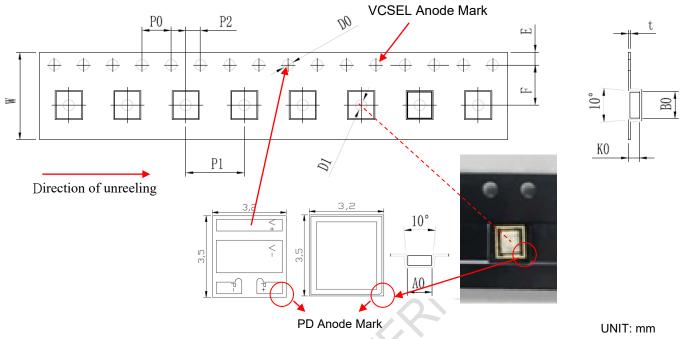
5.1 Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

#### 6. Repairing

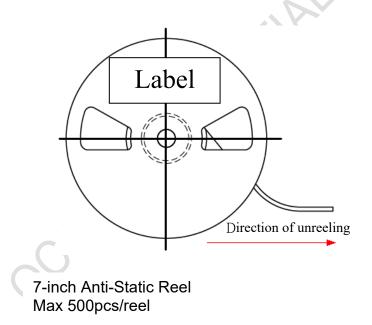
6.1 Repair should not be done after the VCSEL have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the VCSEL will or will not be damaged by repairing.



Carrier Taping



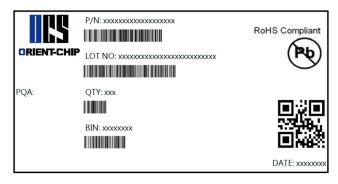
symbol	Ao	Во	Ko	Po	P1	P2	Т
spec	3.45±0.10	3.75±0.10	1.50±0.10	4.00±0.10	8.00±0.10	2.00±0.10	0.30±0.05
symbol	E	F	Do	D1	W	10Po	
spec	1.75±0.10	5.50±0.10	1.50+0.10-0.0	1.50±0.10-0.0	12.00±0.30	40.0±0.10	



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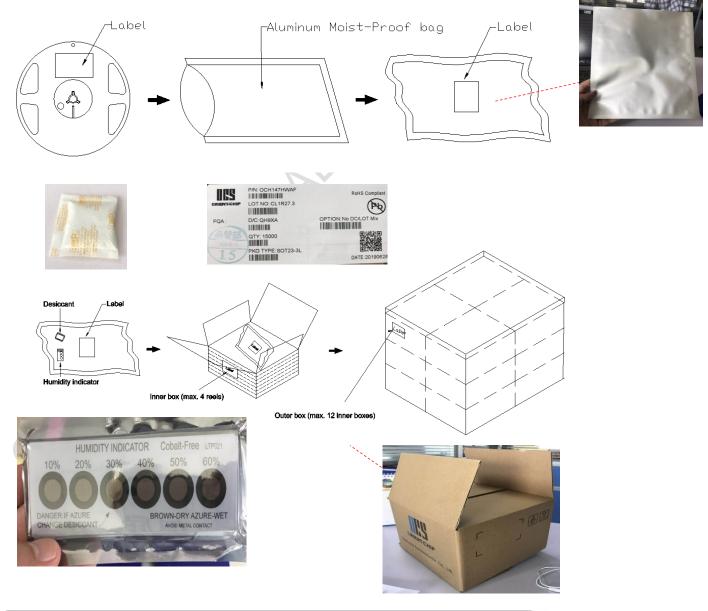


# Product Labeling



- P/N: OCS Product Model Name
- LOT: Lot Number
- QTY: Q'ty
- BIN: mW/nm/Vf ( ex.[A1/94/V1] )
- DATE: Enter the warehouse

# Moisture Resistant Packing





#### Modified records

■ <u>M</u>	odified rec	<u>ords</u>	
	Version	Description	Issue Date
	V0	New spec	2019/03/20
	V1	Add Ith, Slope	2019/10/05
	V2	Update spec	2019/10/14
6	S		
		Page12 - 12	2019/10/14 V2